

What is claimed is

1. A bonding pad for electrically bonding a magnetic head terminal comprising a metal pad having a bonding substance as a surface finishing material.

2. A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is solder.

3. A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a conductive polymer.

4. A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is an adhesive.

5. A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein said bonding substance is a film.

6. A bonding pad for electrically bonding a magnetic head terminal as set forth in claim 1, wherein the solder bump height is approximately 50 –300 μ m, and the solder bump diameter is less than 180 μ m.

7. A disk drive comprising:

a bonding pad for electrically bonding a magnetic head terminal, wherein said bonding pad includes a metal pad having a bonding substance as a surface finishing material.

8. The disk drive as claimed in claim 7, wherein said bonding substance is solder.

9. The disk drive as claimed in claim 7, wherein said bonding substance is a conductive polymer.

10. The disk drive as claimed in claim 7, wherein said bonding substance is an adhesive.

11. The disk drive as claimed in claim 7, wherein said bonding substance is a film.

12. The disk drive as claimed in claim 7, wherein the solder bump height is approximately 50 –300 μ m, and the solder bump diameter is less than 180 μ m.

13. An assemble method for a bonding pad for electrically bonding a magnetic head terminal comprising:

providing a metal pad on an incoming suspension;
planting solder onto said metal pad of said suspension;
potting a slider on said suspension; and

making a heat treatment for said suspension so that said solder on said metal pad adheres to a metal pad of said slider, and becomes a solid state.

14. The method as claimed in claim 13, wherein said bonding substance is solder.

15. The method as claimed in claim 13, wherein said bonding substance is a conductive polymer.

16. The method as claimed in claim 13, wherein said bonding substance is an adhesive.

17. The method as claimed in claim 13, wherein said bonding substance is a film.

18. The method as claimed in claim 13, wherein the solder bump height is approximately 50 –300 μ m, and the solder bump diameter is less than 180 μ m.